

Docket No. 1109.001

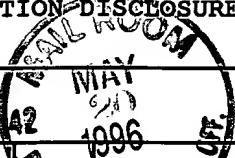
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INFORMATION DISCLOSURE CITATION

Applicant: Eichelberger, C.

Filing Date:

Group: 2811



U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
RP	AA 5,250,843	10/93	Eichelberger	257	692	
RP	BB 5,111,278	5/92	Eichelberger	357	75	
RP	CC 5,091,769	2/92	Eichelberger	357	72	
RP	DD 5,049,980	9/91	Saito et al.	357	80	
RP	EE 4,630,096	12/86	Drye et al.	357	81	
RP	FF 4,907,062	3/90	Fukushima	375	75	
RP	GG 4,860,166	8/89	Nicholls	361	414	
RP	HH 4,827,328	5/89	Ozawa et al.	357	80	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	Date	Country	Class	Subclass	Translation	
						Yes	No
RP	II 62-122258	6/1987	Japan				

Other Documents (including Author, Title, Date, pertinent public. etc.)

	JJ	Fillion et al., "CAD/CIM Requirements in Support of Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Advancing Microelectronics, pp. 8-14, September/October 1994.
Examiner		Date Considered 10/29/97